



Si52146

SKYWORKS®

PCI-EXPRESS GEN 1, GEN 2, GEN 3, & GEN 4 SIX OUTPUT CLOCK GENERATOR

Features

- PCI-Express Gen 1, Gen 2, Gen 3, and Gen 4 common clock compliant
- Gen 3 SRNS Compliant
- Supports Serial-ATA (SATA) at 100 MHz
- Low power push-pull HCSL compatible differential outputs
- No termination resistors required
- Dedicated output enable pins for each clock
- Pin selectable spread control
- Up to six PCI-Express clock outputs
- 25 MHz crystal input or clock input
- I²C support with readback capabilities
- Triangular spread spectrum profile for maximum electromagnetic interference (EMI) reduction
- Industrial temperature: -40 to 85 °C
- 3.3 V Power supply
- 32-pin QFN package

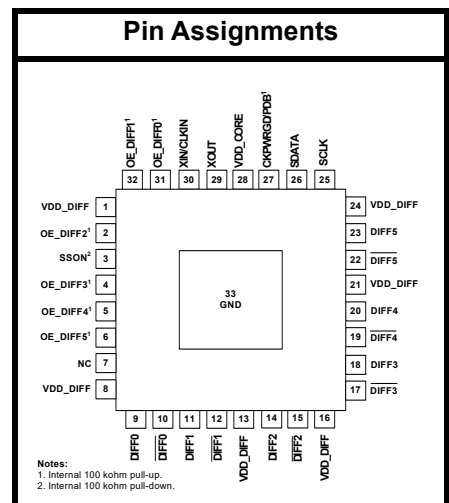
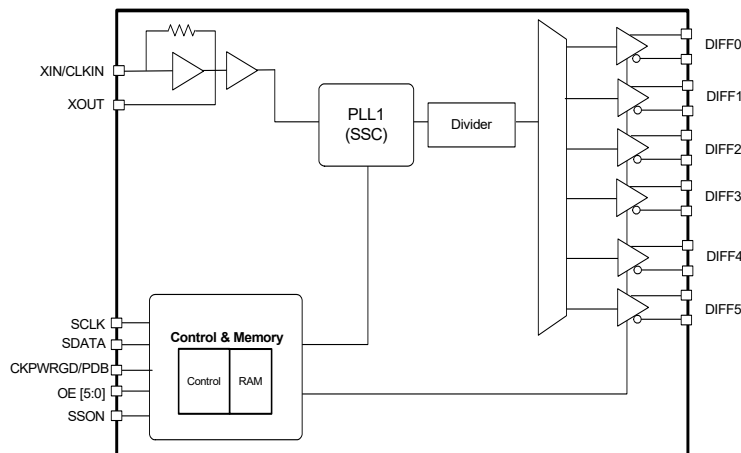
Applications

- Network attached storage
- Multi-function printer
- Wireless access point
- Switches

Description

The Si52146 is a high-performance, PCIe clock generator that can source six PCIe clocks from a 25 MHz crystal or clock input. The clock outputs are compliant to PCIe Gen 1, Gen 2, Gen 3, Gen 3 SRNS and Gen 4 common clock specifications. The device has six output enable control pins for enabling and disabling differential outputs. A spread spectrum control pin for EMI reduction is also available. The small footprint and low power consumption makes the Si52146 the ideal clock solution for consumer and embedded applications. Measuring PCIe clock jitter is quick and easy with the Skyworks Solutions PCIe Clock Jitter Tool. Download it for free at <https://www.skyworksinc.com/en/application-pages/pci-express-learning-center>.

Functional Block Diagram



Patents pending

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1. Electrical Specifications

Table 1. DC Electrical Specifications

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|-------------------------------|----------------------|--|-----------------------|-----|-----------------------|------|
| 3.3 V Operating Voltage | VDD core | 3.3 ±5% | 3.135 | 3.3 | 3.465 | V |
| 3.3 V Input High Voltage | V _{IH} | Control input pins | 2.0 | — | V _{DD} + 0.3 | V |
| 3.3 V Input Low Voltage | V _{IL} | Control input pins | V _{SS} - 0.3 | — | 0.8 | V |
| Input High Voltage | V _{IHI2C} | SDATA, SCLK | 2.2 | — | — | V |
| Input Low Voltage | V _{ILI2C} | SDATA, SCLK | — | — | 1.0 | V |
| Input High Leakage Current | I _{IH} | Except internal pull-down resistors, 0 < V _{IN} < V _{DD} | — | — | 5 | μA |
| Input Low Leakage Current | I _{IL} | Except internal pull-up resistors, 0 < V _{IN} < V _{DD} | -5 | — | — | μA |
| High-impedance Output Current | I _{OZ} | | -10 | — | 10 | μA |
| Input Pin Capacitance | C _{IN} | | 1.5 | — | 5 | pF |
| Output Pin Capacitance | C _{OUT} | | — | — | 6 | pF |
| Pin Inductance | L _{IN} | | — | — | 7 | nH |
| Power Down Current | I _{DD-PD} | | — | — | 1 | mA |
| Dynamic Supply Current | I _{DD_3.3V} | All outputs enabled. Differential clocks with 5" traces and 2 pF load. | — | — | 60 | mA |

Table 2. AC Electrical Specifications

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|--|--------------------|---|------|------|--------------|---------|
| Crystal | | | | | | |
| Long-term Accuracy | L_{ACC} | Measured at $V_{DD}/2$ differential | — | — | 250 | ppm |
| Clock Input | | | | | | |
| CLKIN Duty Cycle | T_{DC} | Measured at $V_{DD}/2$ | 47 | — | 53 | % |
| CLKIN Rise and Fall Times | T_R/T_F | Measured between 0.2 V_{DD} and 0.8 V_{DD} | 0.5 | — | 4.0 | V/ns |
| CLKIN Cycle to Cycle Jitter | T_{CCJ} | Measured at $V_{DD}/2$ | — | — | 250 | ps |
| CLKIN Long Term Jitter | T_{LTJ} | Measured at $V_{DD}/2$ | — | — | 350 | ps |
| Input High Voltage | V_{IH} | XIN/CLKIN pin | 2 | — | $V_{DD}+0.3$ | V |
| Input Low Voltage | V_{IL} | XIN/CLKIN pin | — | — | 0.8 | V |
| Input High Current | I_{IH} | XIN/CLKIN pin, $V_{IN} = V_{DD}$ | — | — | 35 | μA |
| Input Low Current | I_{IL} | XIN/CLKIN pin, $0 < V_{IN} < 0.8$ | -35 | — | — | μA |
| DIFF at 0.7 V | | | | | | |
| Duty Cycle | T_{DC} | Measured at 0 V differential | 45 | — | 55 | % |
| Output-to-Output skew | T_{SKEW} | Measured at 0 V differential | — | — | 800 | ps |
| DIFF Cycle to Cycle Jitter | T_{CCJ} | Measured at 0 V differential | — | 35 | 50 | ps |
| PCIe Gen 1 Pk-Pk, Common Clock | Pk-Pk | PCIe Gen 1 | 0 | 30 | 50 | ps |
| PCIe Gen 2 Phase Jitter, Common Clock | RMS_{GEN2} | $10 \text{ kHz} < F < 1.5 \text{ MHz}$ | 0 | 1.75 | 2.1 | ps |
| PCIe Gen 2 Phase Jitter, Common Clock | RMS_{GEN2} | $1.5 \text{ MHz} < F < \text{Nyquist}$ | 0 | 1.75 | 2.0 | ps |
| PCIe Gen 3 Phase Jitter, Common Clock | RMS_{GEN3} | PLL BW of 2–4 or 2–5 MHz, CDR = 10 MHz | 0 | 0.5 | 0.6 | ps |
| PCIe Gen 3 Phase Jitter, Separate Reference No Spread, SRNS | RMS_{GEN3_SRNS} | PLL BW of 2–4 or 2–5 MHz, CDR = 10 MHz | — | 0.35 | 0.42 | ps |
| PCIe Gen 4 Phase Jitter, Common Clock | RMS_{GEN4} | PLL BW of 2–4 or 2–5 MHz, CDR = 10 MHz | — | 0.5 | 0.6 | ps |
| Long Term Accuracy | L_{ACC} | Measured at 0 V differential | — | — | 100 | ppm |
| Rising/Falling Slew Rate | T_R/T_F | Measured differentially from $\pm 150 \text{ mV}$ | 1 | — | 8 | V/ns |
| Voltage High | V_{HIGH} | | — | — | 1.15 | V |
| Voltage Low | V_{LOW} | | -0.3 | — | — | V |
| Crossing Point Voltage at 0.7 V Swing | V_{OX} | | 300 | — | 550 | mV |
| Notes: | | | | | | |
| 1. Visit https://www.pcisig.com for complete PCIe specifications. | | | | | | |
| 2. Gen 4 specifications based on the PCI-Express Base Specification 4.0 rev. 0.5. | | | | | | |
| 3. Download the Skyworks Solutions PCIe Clock Jitter Tool at https://www.skyworksinc.com/en/application-pages/pci-express-learning-center . | | | | | | |

Table 2. AC Electrical Specifications (Continued)

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|--|---------------------|--|------|------|-----|------|
| Spread Range | SPR-2 | Down spread | — | −0.5 | — | % |
| Modulation Frequency | F _{MOD} | | 30 | 31.5 | 33 | kHz |
| Enable/Disable and Setup | | | | | | |
| Clock Stabilization from Power-up | T _{STABLE} | Measured from the point both V _{DD} and clock input are valid | — | — | 1.8 | ms |
| Stopclock Set-up Time | T _{SS} | | 10.0 | — | — | ns |
| Notes: | | | | | | |
| <ol style="list-style-type: none"> 1. Visit https://www.pcisig.com for complete PCIe specifications. 2. Gen 4 specifications based on the PCI-Express Base Specification 4.0 rev. 0.5. 3. Download the Skyworks Solutions PCIe Clock Jitter Tool at https://www.skyworksinc.com/en/application-pages/pci-express-learning-center. | | | | | | |

Table 3. Absolute Maximum Conditions

| Parameter | Symbol | Test Condition | Min | Typ | Max | Unit |
|---|----------------------|-----------------------------|------|-----|-----|-----------------|
| Main Supply Voltage | V _{DD_3.3V} | Functional | — | — | 4.6 | V |
| Input Voltage | V _{IN} | Relative to V _{SS} | −0.5 | — | 4.6 | V _{DC} |
| Temperature, Storage | T _S | Non-functional | −65 | — | 150 | °C |
| Temperature, Operating Ambient | T _A | Functional | −40 | — | 85 | °C |
| Temperature, Junction | T _J | Functional | — | — | 150 | °C |
| Dissipation, Junction to Case | Ø _{JC} | JEDEC (JESD 51) | — | — | 17 | °C/W |
| Dissipation, Junction to Ambient | Ø _{JA} | JEDEC (JESD 51) | — | — | 35 | °C/W |
| ESD Protection (Human Body Model) | ESD _{HBM} | JEDEC (JESD 22-A114) | 2000 | — | — | V |
| Flammability Rating | UL-94 | UL (Class) | V-0 | | | |
| Note: While using multiple power supplies, the voltage on any input or I/O pin cannot exceed the power pin during power-up. Power supply sequencing is not required. | | | | | | |

2. Functional Description

2.1. Crystal Recommendations

If using crystal input, the device requires a parallel resonance 25 MHz crystal.

Table 4. Crystal Recommendations

| Frequency (Fund) | Cut | Loading | Load Cap | Shunt Cap (max) | Motional (max) | Tolerance (max) | Stability (max) | Aging (max) |
|------------------|-----|----------|----------|-----------------|----------------|-----------------|-----------------|-------------|
| 25 MHz | AT | Parallel | 12–15 pF | 5 pF | 0.016 pF | 35 ppm | 30 ppm | 5 ppm |

2.1.1. Crystal Loading

Crystal loading is critical in achieving low ppm performance. In order to achieve low zero ppm error, use the calculations in section 2.1.2 to estimate the appropriate capacitive loading (CL).

Figure 1 shows a typical crystal configuration using the two trim capacitors. It is important that the trim capacitors are in series with the crystal.

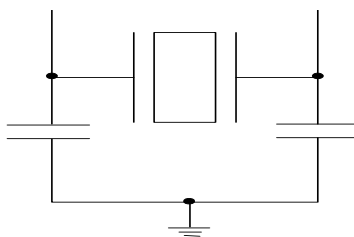


Figure 1. Crystal Capacitive Clarification

2.1.2. Calculating Load Capacitors

In addition to the standard external trim capacitors, consider the trace capacitance and pin capacitance to calculate the crystal loading correctly. The capacitance on each side is in series with the crystal. The total capacitance on both sides is twice the specified crystal load capacitance (CL). Trim capacitors are calculated to provide equal capacitive loading on both sides.

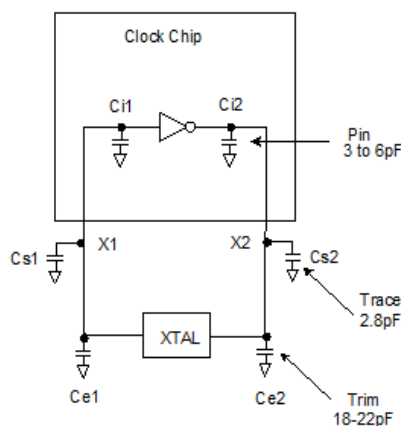


Figure 2. Crystal Loading Example

Use the following formulas to calculate the trim capacitor values for Ce1 and Ce2.

Load Capacitance (each side)

$$C_e = 2 \times CL - (C_s + C_i)$$

Total Capacitance (as seen by the crystal)

$$CL_e = \frac{1}{\left(\frac{1}{C_{e1} + C_{s1} + C_{i1}} + \frac{1}{C_{e2} + C_{s2} + C_{i2}} \right)}$$

- CL: Crystal load capacitance
- CL_e: Actual loading seen by crystal using standard value trim capacitors
- C_e: External trim capacitors
- C_s: Stray capacitance (terraced)
- C_i: Internal capacitance (lead frame, bond wires, etc.)

2.2. CKPWRGD/PDB (Power Down) Pin

The CKPWRGD/PDB pin is a dual-function pin. During initial power up, the pin functions as the CKPWRGD pin. Upon the first power up, if the CKPWRGD pin is low, the outputs will be disabled, but the crystal oscillator and I²C logics will be active. Once the CKPWRGD pin has been sampled high by the clock chip, the pin assumes a PDB functionality. When the pin has assumed a PDB functionality and is pulled low, the device will be placed in power down mode. The CKPWRGD/PDB pin is required to be driven at all times even though it has an internal 100 kΩ resistor.

2.3. PDB (Power Down) Assertion

The PDB pin is an asynchronous active low input used to disable all output clocks in a glitch-free manner. All outputs will be driven low in power down mode. In power down mode, all outputs, the crystal oscillator, and the I²C logic are disabled.

2.4. PDB Deassertion

When a valid rising edge on CKPWRGD/PDB pin is applied, all outputs are enabled in a glitch-free manner within two to six output clock cycles.

2.5. OE Pin

The OE pin is an active high input used to enable and disable the output clock. To enable the output clock, the OE pin and the I²C OE bit need to be a logic high. By default, the OE pin and the I²C OE bit are set to a logic high. There are two methods to disable the output clock: the OE pin is pulled to a logic low, or the I²C OE bit is set to a logic low. The OE pin is required to be driven at all times even though it has an internal 100 kΩ resistor.

2.6. OE Assertion

The OE pin is an active high input used for synchronous stopping and starting the respective output clock while the rest of the clock generator continues to function. The assertion of the OE function is achieved by pulling the OE pin and the I²C OE bit high which causes the respective stopped output to resume normal operation. No short or stretched clock pulses are produced when the clocks resume. The maximum latency from the assertion to active outputs is no more than two to six output clock cycles.

2.7. OE Deassertion

The OE function is deasserted by pulling the pin or the I²C OE bit to a logic low. The corresponding output is stopped cleanly and the final output state is driven low.

2.8. SSON Pin

The SSON pin is an active input used to enable –0.5% spread spectrum on the outputs. When sampled high, –0.5% spread is enabled on the output clocks. When sampled low, the output clocks are non-spread.

3. Test and Measurement Setup

Figure 3 shows the test load configuration for the HCSL compatible clock outputs.

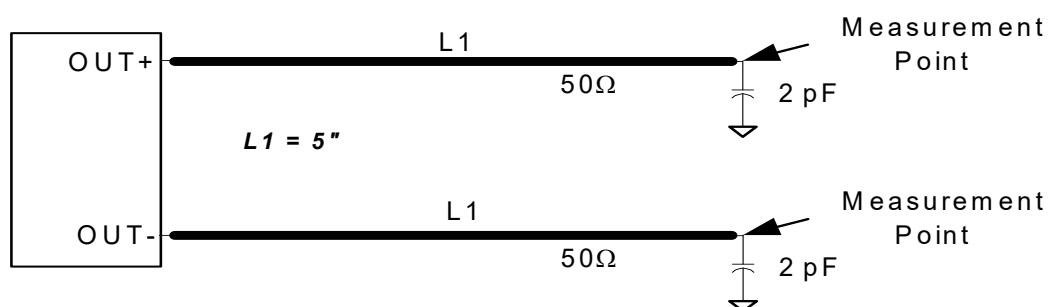


Figure 3. 0.7 V Differential Load Configuration

Please reference application note AN781 for recommendations on how to terminate the differential outputs for LVDS, LVPECL, or CML signalling levels.

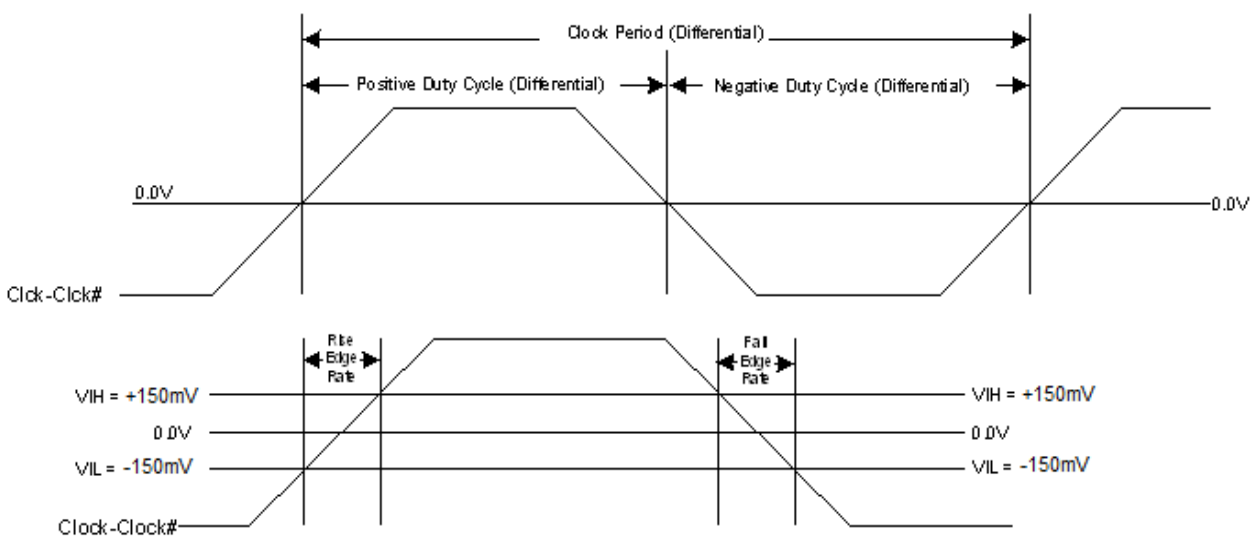


Figure 4. Differential Output Signals (for AC Parameters Measurement)

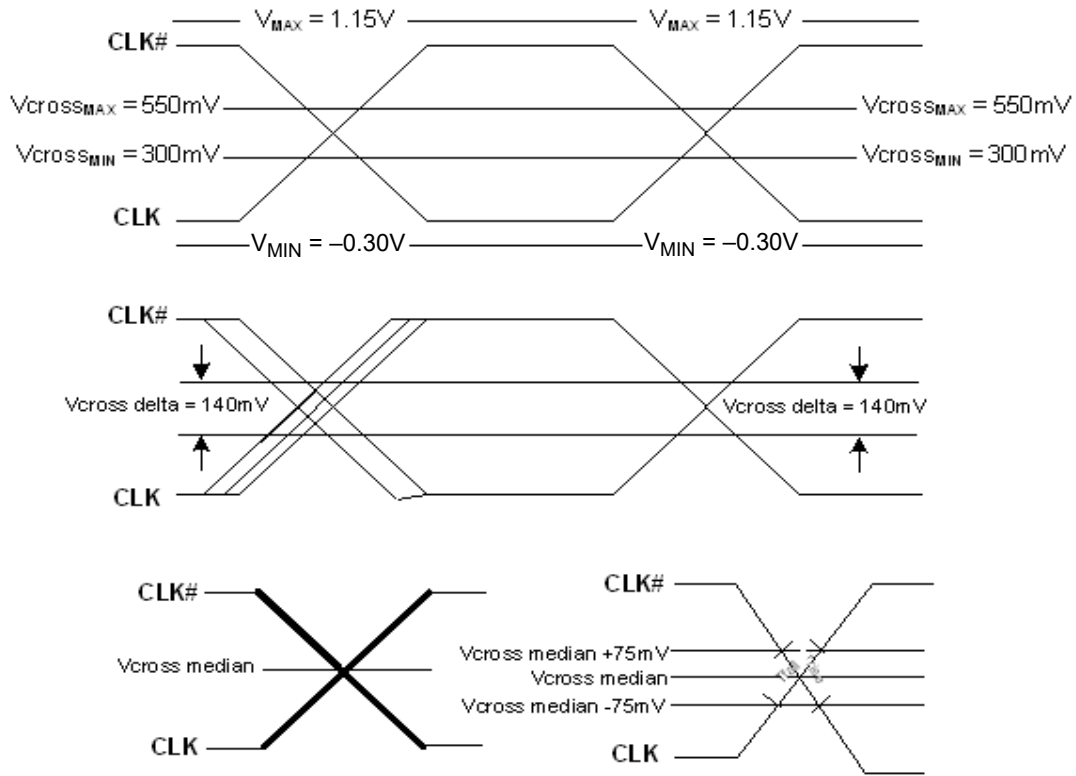


Figure 5. Single-ended Measurement for Differential Output Signals (for AC Parameters Measurement)

4. Control Registers

4.1. I²C Interface

To enhance the flexibility and function of the clock synthesizer, an I²C interface is provided. Through the I²C interface, various device functions are available, such as individual clock output enablement. The registers associated with the I²C interface initialize to their default setting at power-up. The use of this interface is optional. Clock device register changes are normally made at system initialization, if any are required.

4.2. Data Protocol

The clock driver I²C protocol accepts byte write, byte read, block write, and block read operations from the controller. For block write/read operation, access the bytes in sequential order from lowest to highest (most significant bit first) with the ability to stop after any complete byte is transferred. For byte write and byte read operations, the system controller can access individually indexed bytes. .

The block write and block read protocol is outlined in Table 5 while Table 6 outlines byte write and byte read protocol. The slave receiver address is 11010110 (D6h).

Table 5. Block Read and Block Write Protocol

| Block Write Protocol | | Block Read Protocol | |
|----------------------|------------------------------|---------------------|-----------------------------------|
| Bit | Description | Bit | Description |
| 1 | Start | 1 | Start |
| 8:2 | Slave address—7 bits | 8:2 | Slave address—7 bits |
| 9 | Write | 9 | Write |
| 10 | Acknowledge from slave | 10 | Acknowledge from slave |
| 18:11 | Command Code—8 bits | 18:11 | Command Code—8 bits |
| 19 | Acknowledge from slave | 19 | Acknowledge from slave |
| 27:20 | Byte Count—8 bits | 20 | Repeat start |
| 28 | Acknowledge from slave | 27:21 | Slave address—7 bits |
| 36:29 | Data byte 1—8 bits | 28 | Read = 1 |
| 37 | Acknowledge from slave | 29 | Acknowledge from slave |
| 45:38 | Data byte 2—8 bits | 37:30 | Byte Count from slave—8 bits |
| 46 | Acknowledge from slave | 38 | Acknowledge |
| | Data Byte/Slave Acknowledges | 46:39 | Data byte 1 from slave—8 bits |
| | Data Byte N—8 bits | 47 | Acknowledge |
| | Acknowledge from slave | 55:48 | Data byte 2 from slave—8 bits |
| | Stop | 56 | Acknowledge |
| | | | Data bytes from slave/Acknowledge |
| | | | Data Byte N from slave—8 bits |
| | | | NOT Acknowledge |
| | | | Stop |

Table 6. Byte Read and Byte Write Protocol

| Byte Write Protocol | | Byte Read Protocol | |
|----------------------------|------------------------|---------------------------|------------------------|
| Bit | Description | Bit | Description |
| 1 | Start | 1 | Start |
| 8:2 | Slave address–7 bits | 8:2 | Slave address–7 bits |
| 9 | Write | 9 | Write |
| 10 | Acknowledge from slave | 10 | Acknowledge from slave |
| 18:11 | Command Code–8 bits | 18:11 | Command Code–8 bits |
| 19 | Acknowledge from slave | 19 | Acknowledge from slave |
| 27:20 | Data byte–8 bits | 20 | Repeated start |
| 28 | Acknowledge from slave | 27:21 | Slave address–7 bits |
| 29 | Stop | 28 | Read |
| | | 29 | Acknowledge from slave |
| | | 37:30 | Data from slave–8 bits |
| | | 38 | NOT Acknowledge |
| | | 39 | Stop |

Control Register 0. Byte 0

| Bit | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|------|-----|-----|-----|-----|-----|-----|-----|-----|
| Name | | | | | | | | |
| Type | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

Reset settings = 00000000

| Bit | Name | Function |
|-----|----------|----------|
| 7:0 | Reserved | |

Register 1. Byte 1

| Bit | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|------|-----|-----|-----|----------|-----|----------|-----|----------|
| Name | | | | DIFF0_OE | | DIFF1_OE | | DIFF2_OE |
| Type | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

Reset settings = 00010101

| Bit | Name | Function |
|-----|----------|--|
| 7:5 | Reserved | |
| 4 | DIFF0_OE | Output Enable for DIFF0. 0: Output disabled. 1: Output Enabled. |
| 3 | Reserved | |
| 2 | DIFF1_OE | Output Enable for DIFF1. 0: Output disabled. 1: Output enabled. |
| 1 | Reserved | |
| 0 | DIFF2_OE | Output Enable for DIFF2. 0: Output disabled. 1: Output enabled. |

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Register 2. Byte 2

| Bit | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|------|----------|----------|----------|-----|-----|-----|-----|-----|
| Name | DIFF3_OE | DIFF4_OE | DIFF5_OE | | | | | |
| Type | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

Reset settings = 11100000

| Bit | Name | Function |
|-----|----------|--|
| 7 | DIFF3_OE | Output Enable for DIFF3. 0: Output disabled. 1: Output enabled. |
| 6 | DIFF4_OE | Output Enable for DIFF4. 0: Output disabled. 1: Output enabled. |
| 5 | DIFF5_OE | Output Enable for DIFF5. 0: Output disabled. 1: Output enabled. |
| 4:0 | Reserved | |

Register 3. Byte 3

| Bit | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|------|---------------|-----|-----|-----|----------------|-----|-----|-----|
| Name | Rev Code[3:0] | | | | Vendor ID[3:0] | | | |
| Type | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

Reset settings = 00001000

| Bit | Name | Function |
|-----|----------------|------------------------------------|
| 7:4 | Rev Code[3:0] | Program Revision Code. |
| 3:0 | Vendor ID[3:0] | Vendor Identification Code. |

Register 4. Byte 4

| Bit | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|-------------|---------|-----|-----|-----|-----|-----|-----|-----|
| Name | BC[7:0] | | | | | | | |
| Type | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

Reset settings = 00000110

| Bit | Name | Function |
|-----|---------|-----------------------------|
| 7:0 | BC[7:0] | Byte Count Register. |

Register 5. Byte 5

| Bit | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|-------------|--------------|------------------|------------------|------------------|-----|-----|-----|-----|
| Name | DIFF_Amp_Sel | DIFF_Amp_Cntl[2] | DIFF_Amp_Cntl[1] | DIFF_Amp_Cntl[0] | | | | |
| Type | R/W | R/W | R/W | R/W | R/W | R/W | R/W | R/W |

Reset settings = 11011000

| Bit | Name | Function |
|-----|------------------|--|
| 7 | DIFF_Amp_Sel | Amplitude Control for DIFF Differential Outputs. 0: Differential outputs with Default amplitude. 1: Differential outputs amplitude is set by Byte 5[6:4]. |
| 6 | DIFF_Amp_Cntl[2] | DIFF Differential Outputs Amplitude Adjustment. 000: 300 mV 001: 400 mV 010: 500 mV 011: 600 mV 100: 700 mV 101: 800 mV 110: 900 mV 111: 1000 mV |
| 5 | DIFF_Amp_Cntl[1] | |
| 4 | DIFF_Amp_Cntl[0] | |
| 3:0 | Reserved | |

5. Pin Descriptions: 32-Pin QFN

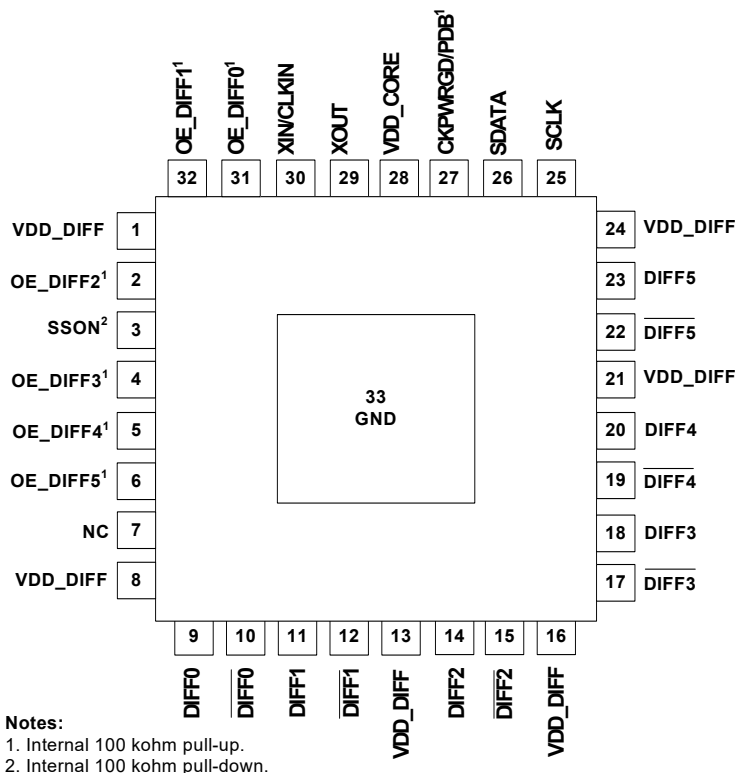


Table 7. Si52146 32-Pin QFN Descriptions

| Pin # | Name | Type | Description |
|-------|---------------------------|--------|---|
| 1 | VDD_DIFF | PWR | 3.3 V power supply |
| 2 | OE_DIFF2 | I,PU | Active high input pin enables DIFF2 (internal 100 kΩ pull-up). |
| 3 | SSON | I, PD | Active high input pin enables –0.5% spread on DIFF clocks (internal 100 kΩ pull-down) |
| 4 | OE_DIFF3 | I,PU | Active high input pin enables DIFF3 (internal 100 kΩ pull-up). |
| 5 | OE_DIFF4 | I,PU | Active high input pin enables DIFF4 (internal 100 kΩ pull-up). |
| 6 | OE_DIFF5 | I,PU | Active high input pin enables DIFF5 (internal 100 kΩ pull-up). |
| 7 | NC | NC | No connect |
| 8 | VDD_DIFF | PWR | 3.3 V power supply |
| 9 | DIFF0 | O, DIF | 0.7 V, 100 MHz differential clock output |
| 10 | $\overline{\text{DIFF0}}$ | O, DIF | 0.7 V, 100 MHz differential clock output |
| 11 | DIFF1 | O, DIF | 0.7 V, 100 MHz differential clock output |
| 12 | $\overline{\text{DIFF1}}$ | O, DIF | 0.7 V, 100 MHz differential clock output |

Table 7. Si52146 32-Pin QFN Descriptions (Continued)

| Pin # | Name | Type | Description |
|-------|---------------------------|--------|--|
| 13 | VDD_DIFF | PWR | 3.3 V power supply |
| 14 | DIFF2 | O, DIF | 0.7 V, 100 MHz differential clock output |
| 15 | $\overline{\text{DIFF2}}$ | O, DIF | 0.7 V, 100 MHz differential clock output |
| 16 | VDD_DIFF | PWR | 3.3 V power supply |
| 17 | $\overline{\text{DIFF3}}$ | O, DIF | 0.7 V, 100 MHz differential clock output |
| 18 | DIFF3 | O, DIF | 0.7 V, 100 MHz differential clock output |
| 19 | $\overline{\text{DIFF4}}$ | O, DIF | 0.7 V, 100 MHz differential clock output |
| 20 | DIFF4 | O, DIF | 0.7 V, 100 MHz differential clock output |
| 21 | VDD_DIFF | PWR | 3.3 V power supply |
| 22 | $\overline{\text{DIFF5}}$ | O, DIF | 0.7 V, 100 MHz differential clock output |
| 23 | DIFF5 | O, DIF | 0.7 V, 100 MHz differential clock output |
| 24 | VDD_DIFF | PWR | 3.3 V power supply |
| 25 | SCLK | I | I ² C compatible SCLOCK |
| 26 | SDATA | I/O | I ² C compatible SDATA |
| 27 | CKPWRGD/PDB | I, PU | Active low input for asserting power down (PDB) and disabling all outputs (internal 100 k Ω pull-up). |
| 28 | VDD_CORE | PWR | 3.3 V power supply |
| 29 | XOUT | O | 25.00 MHz crystal output, Float XOUT if using only CLKIN (clock input) |
| 30 | XIN/CLKIN | I | 25.00 MHz crystal input or 3.3 V, 25 MHz clock input |
| 31 | OE_DIFF0 | I,PU | Active high input pin enables DIFF0 (internal 100 k Ω pull-up). |
| 32 | OE_DIFF1 | I,PU | Active high input pin enables DIFF1 (internal 100 k Ω pull-up). |
| 33 | GND | GND | Ground for bottom pad of the IC. |

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6. Ordering Guide

| Part Number | Package Type | Temperature |
|------------------|--------------------------|--------------------------|
| Lead-free | | |
| Si52146-A01AGM | 32-pin QFN | Industrial, -40 to 85 °C |
| Si52146-A01AGMR | 32-pin QFN—Tape and Reel | Industrial, -40 to 85 °C |

8. Land Pattern

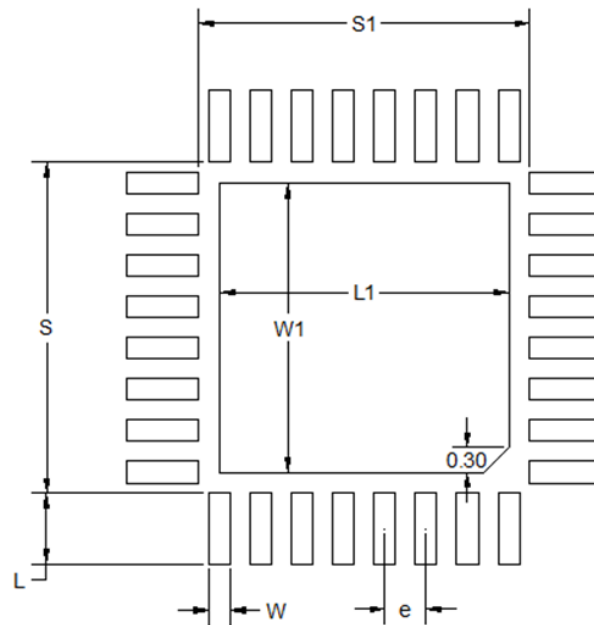


Figure 7. QFN Land Pattern

Table 9. Land Pattern Dimensions

| Dimension | mm |
|-----------|------|
| S1 | 4.01 |
| S | 4.01 |
| L1 | 3.20 |
| W1 | 3.20 |
| e | 0.50 |
| W | 0.26 |

Table 9. Land Pattern Dimensions

| L | 0.86 |
|---|------|
| <p>Notes:</p> <p>General</p> <ol style="list-style-type: none"> 1. All dimensions shown are in millimeters (mm) unless otherwise noted. 2. This Land Patter Design is based on the IPC-7351 guidelines. <p>Solder Mask Design</p> <ol style="list-style-type: none"> 3. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μm minimum, all the way around the pad. <p>Stencil Design</p> <ol style="list-style-type: none"> 4. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release. 5. The stencil thickness should be 0.125 mm (5 mils). 6. The ratio of stencil aperture to land pad size can be 1:1 for all perimeter pads. 7. A 3x3 array of 0.85 mm square openings on a 1.00mm pitch can be used for the center ground pad. <p>Card Assembly</p> <ol style="list-style-type: none"> 8. A No-Clean, Type-3 solder paste is recommended. 9. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components. | |

DOCUMENT CHANGE LIST

Revision 0.1 to Revision 1.0

- Updated Pin Names.
- Updated Table 1.
- Updated Table 2.
- Updated Table 3.
- Updated section 2.1.
- Updated section 2.1.1.
- Updated sections 2.2 through 2.8.
- Updated section 4.2.
- Updated Table 7.

Revision 1.0 to Revision 1.1

- Removed Moisture Sensitivity Level specification from Table 3.

Revision 1.1 to Revision 1.2

- Updated Table 2.
- Updated section 3.

Revision 1.2 to Revision 1.3

- Updated Features on page 1
- Updated Description on page 1.
- Updated specs in Table 2, “AC Electrical Specifications,” on page 5.
- Updated the package outline.

Revision 1.3 to Revision 1.4

- Added test condition for Tstable in Table 2.